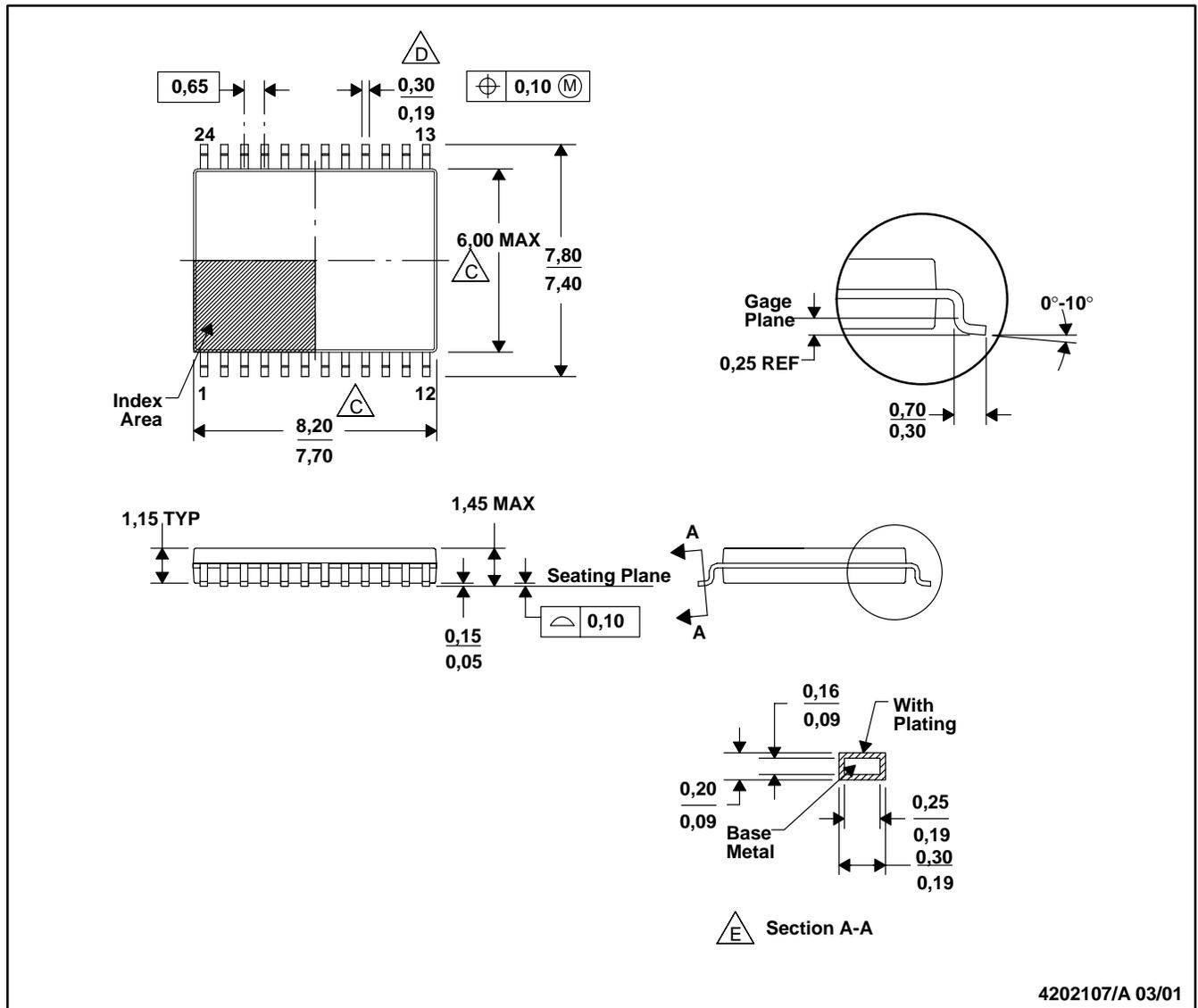


DCV (R-PSOP-G24)

PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusions, but do include mold mismatch and are measured at datum plane, mold parting line. Mold flash or protrusion shall not exceed 0,20mm per side.
 - D. Lead width dimension does not include dambar protrusion/ intrusion. Allowable dambar protrusion shall be 0,13mm total in excess of width dimension at maximum material condition. Dambar intrusion shall not reduce width dimension by more than 0,07mm at least material condition.
 - E. All dimensions in Section A-A apply to the flat section of the lead between 0,10mm and 0,25mm from the lead tips.
 - F. A visual index feature must be located within the cross-hatched area.

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